

# TSA65N25M

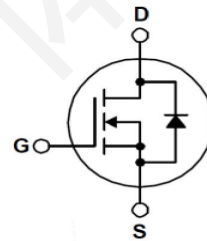
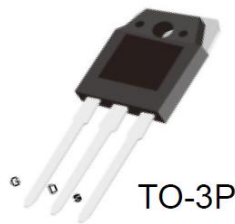
## 250V N-Channel MOSFET

### General Description

This Power MOSFET is produced using Truesemi's advanced planar stripe DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

### Features

- 65A, 250V, Max. RDS(on)=0.05Ω @ VGS = 10V
- Low gate charge: Qg=115nC (Typ.)
- 100% avalanche tested
- RoHS compliant device



### Absolute Maximum Ratings Tc=25°C unless otherwise specified

Symbol	Parameter	Value	Units
V <sub>DSS</sub>	Drain-Source Voltage	250	V
V <sub>GS</sub>	Gate-Source Voltage	± 30	V
I <sub>D</sub>	Drain Current	T <sub>C</sub> = 25°C	65
		T <sub>C</sub> = 100°C	41
I <sub>DM</sub>	Pulsed Drain Current *	260	A
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)	3200	mJ
I <sub>AS</sub>	Repetitive avalanche current (Note 2)	32	A
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)	19.8	mJ
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> = 25°C)	198	W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to +150	°C

\* Limited only maximum junction temperature

### Thermal Resistance Characteristics

Symbol	Parameter	Typ.	Max.	Units
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case	--	0.63	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	--	62.5	°C/W

**Electrical Characteristics**  $T_c=25\text{ }^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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**On Characteristics**

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2.0	--	4.0	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 32.5\text{ A}$	--	0.04	0.05	$\Omega$
$R_g$	Internal gate resistance	Open drain, $f=1\text{ MHz}$	--	0.8	--	$\Omega$

**Off Characteristics**

$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	250	--	--	V
$I_{DSS}$	Drain-source cut-off current	$V_{DS} = 300\text{ V}, V_{GS} = 0\text{ V}$	--	--	1	$\mu\text{A}$
		$V_{DS} = 300\text{ V}, T_c = 125\text{ }^\circ\text{C}$	--	--	100	$\mu\text{A}$
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA

**Dynamic Characteristics**

$C_{iss}$	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	5050	--	pF
$C_{oss}$	Output Capacitance		--	593	--	pF
$C_{rss}$	Reverse Transfer Capacitance		--	68	--	pF

**Switching Characteristics**

$t_{d(on)}$	Turn-On Time	$V_{DD} = 125\text{ V}, I_D = 65\text{ A},$ $R_G = 25\text{ }\Omega$ (Note 3,4)	--	68	--	ns
$t_r$	Turn-On Rise Time		--	33	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	269	--	ns
$t_f$	Turn-Off Fall Time		--	46	--	ns
$Q_g$	Total Gate Charge	$V_{DS} = 200\text{ V}, I_D = 65\text{ A},$ $V_{GS} = 10\text{ V}$ (Note 3,4)	--	115	--	nC
$Q_{gs}$	Gate-Source Charge		--	28	--	nC
$Q_{gd}$	Gate-Drain Charge		--	41	--	nC

**Source-Drain Diode Maximum Ratings and Characteristics**

$I_S$	Continuous Source-Drain Diode Forward Current		--	--	65	A
$I_{SM}$	Pulsed Source-Drain Diode Forward Current		--	--	260	
$V_{SD}$	Source-Drain Diode Forward Voltage	$I_S = 65\text{ A}, V_{GS} = 0\text{ V}$	--	--	1.5	V
$t_{rr}$	Reverse Recovery Time	$I_S = 65\text{ A}, V_{GS} = 0\text{ V}$ $di_p/dt = 100\text{ A}/\mu\text{s}$ (Note 3, 4)	--	338	--	ns
$Q_{rr}$	Reverse Recovery Charge		--	3.24	--	$\mu\text{C}$

**NOTES:**

1. Repeated rating: Pulse width limited by safe operating area
2.  $L=5\text{ mH}, I_{AS}=32\text{ A}, V_{DD}=50\text{ V}, R_G=25\text{ }\Omega,$  Starting  $T_J=25\text{ }^\circ\text{C}$
3. Pulse test: Pulse width  $\leq 300\text{ }\mu\text{s},$  Duty cycle  $\leq 2\%$
4. Essentially Independent of Operating Temperature Typical Characteristics

Typical Characteristics

Fig. 1  $I_D - V_{DS}$

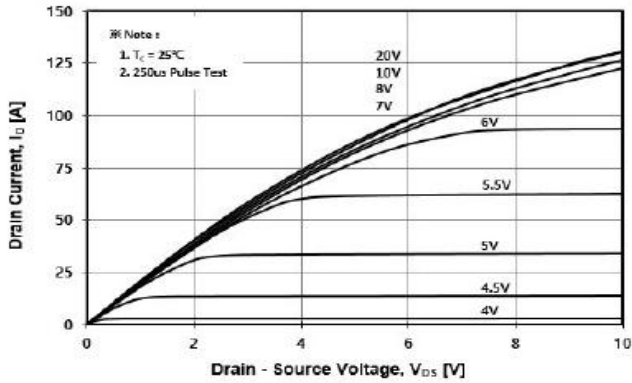


Fig. 2  $I_D - V_{GS}$

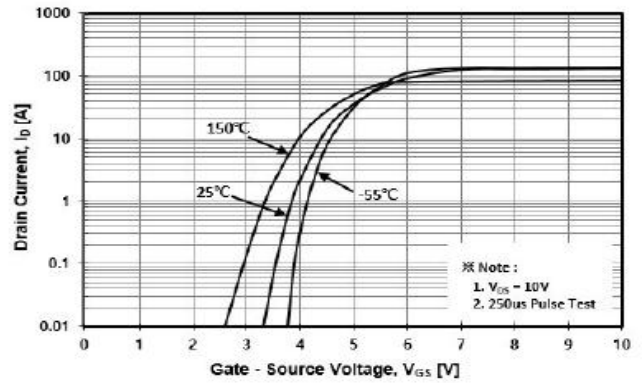


Fig. 3  $R_{DS(ON)} - I_D$

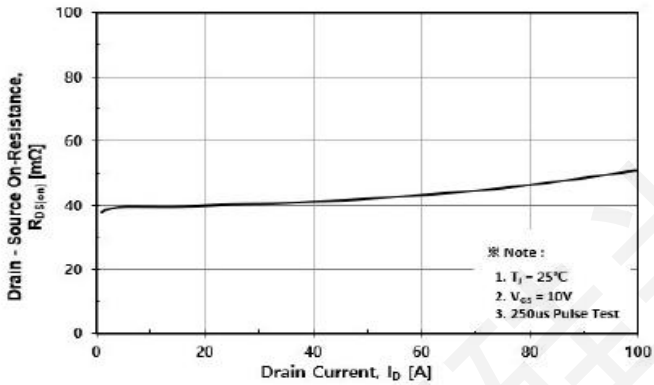


Fig. 4  $I_S - V_{SD}$

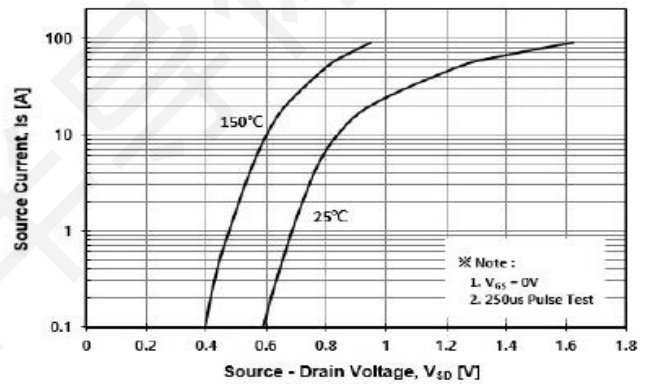


Fig. 5 Capacitance -  $V_{DS}$

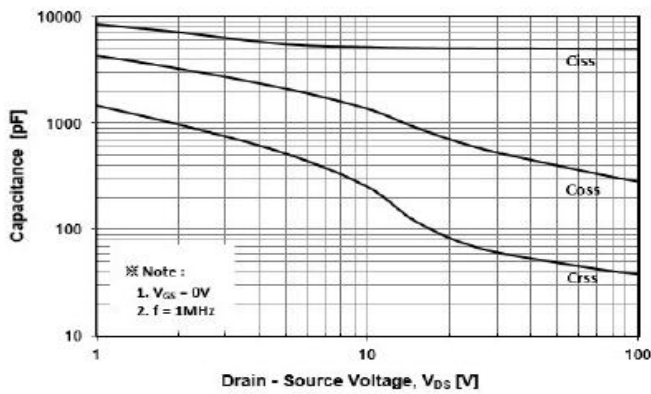
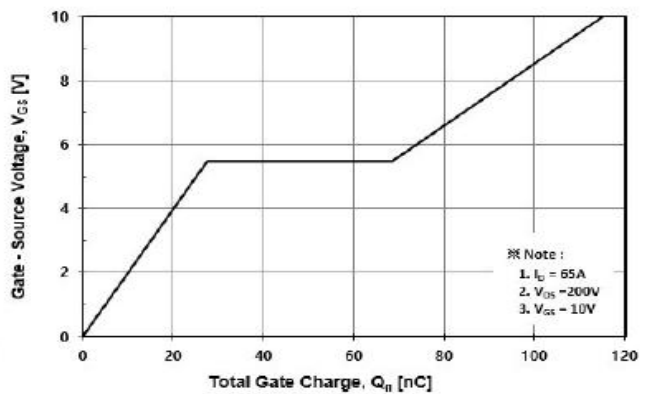


Fig. 6  $V_{GS} - Q_G$



Typical Characteristics Curve (Continue)

Fig. 7  $BV_{DSS} - T_J$

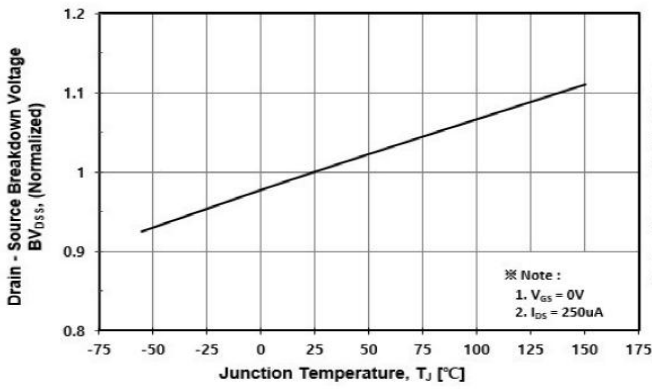


Fig. 8  $R_{DS(ON)} - T_J$

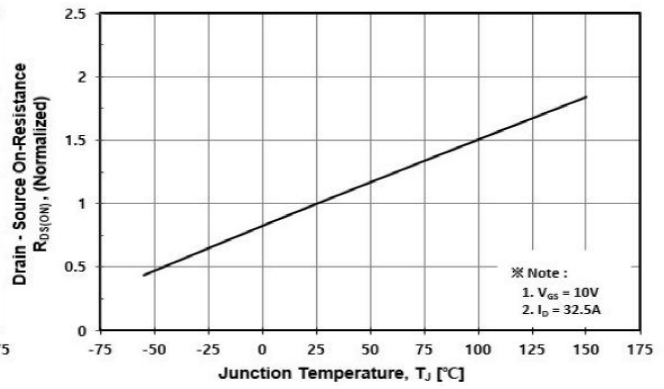


Fig. 9  $I_D - T_C$

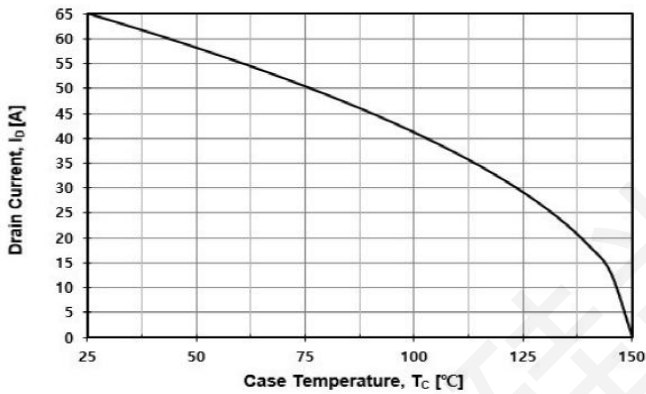


Fig. 10 Safe Operating Area

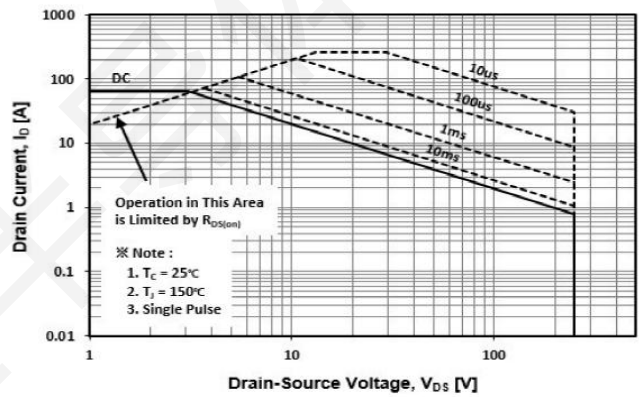


Fig. 11 Transient Thermal Impedance

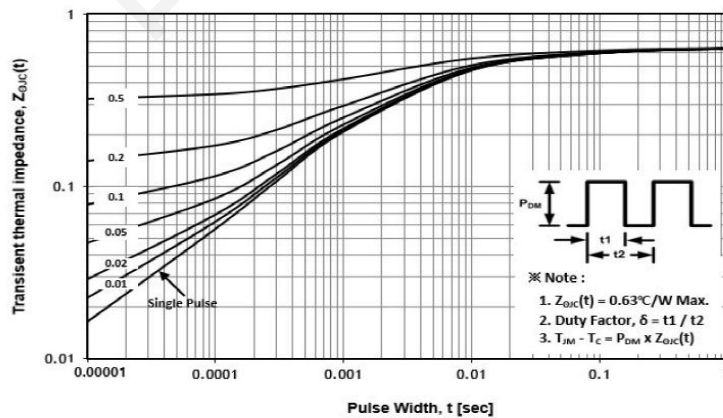


Fig. 12 Gate Charge Test Circuit & Waveform

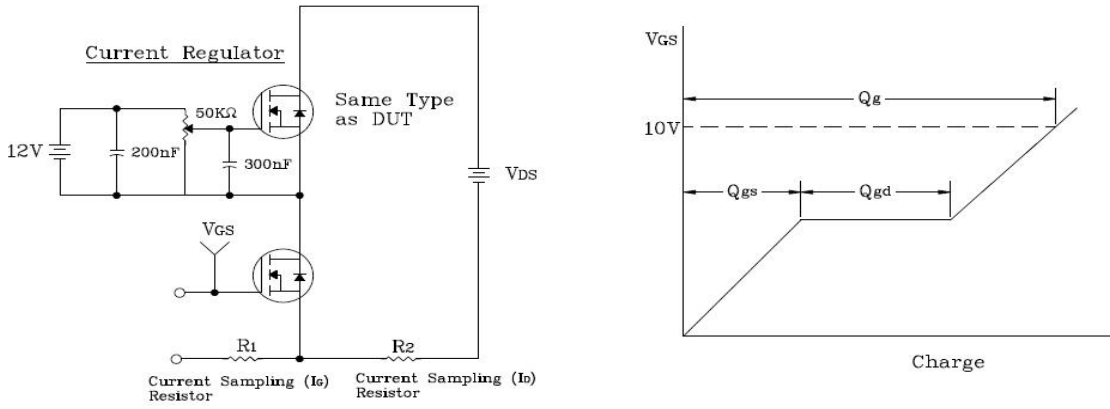


Fig. 13 Resistive Switching Test Circuit & Waveform

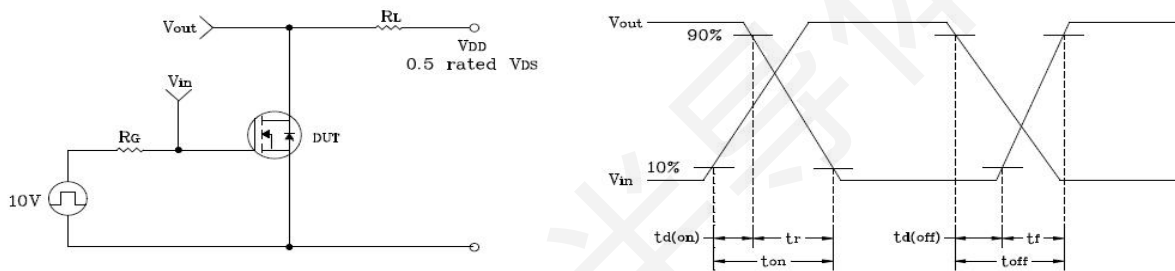


Fig. 14  $E_{AS}$  Test Circuit & Waveform

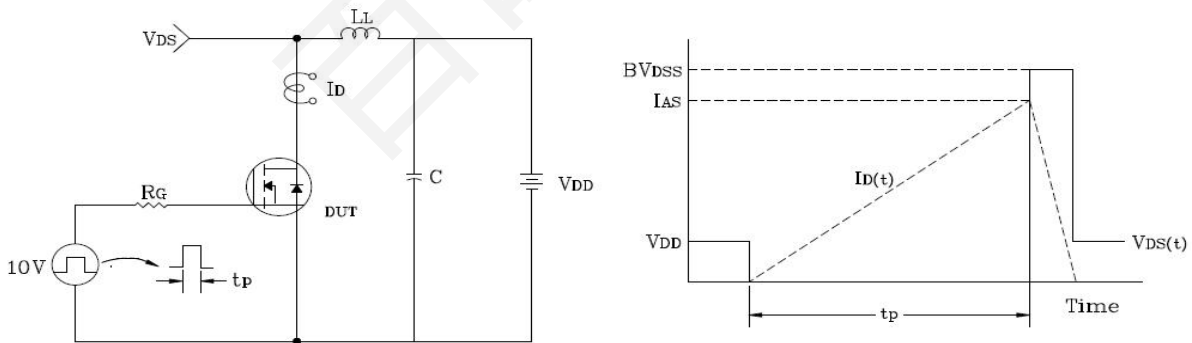


Fig. 15 Diode Reverse Recovery Time Test Circuit & Waveform

